

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
10 August 2023 (10.08.2023)



(10) International Publication Number
WO 2023/150026 A1

(51) International Patent Classification:

G01N 23/225 (2006.01) H01J 37/10 (2006.01)
G01N 23/2204 (2018.01) H01J 37/20 (2006.01)
H01J 37/05 (2006.01) H01L 21/66 (2006.01)

(21) International Application Number:

PCT/US2023/011088

(22) International Filing Date:

18 January 2023 (18.01.2023)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

17/591,569 02 February 2022 (02.02.2022) US

(71) Applicant: **KLA CORPORATION** [US/US]; One Technology Drive, LEGAL DEPARTMENT, Milpitas, California 95035 (US).

(72) Inventors: **JIANG, Youfei**; 1190 Fallen Leaf Drive, Milpitas, California 95035 (US). **STEIGERWALD, Michael**; 440 Dixon Landing Road, Milpitas, California 95035 (US). **SEARS, Christopher**; 10594 SE Isaac Drive, Happy Valley, Oregon 97086 (US).

(74) Agent: **MCANDREWS, Kevin** et al.; LEGAL DEPARTMENT, One Technology Drive, Milpitas, California 95035 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

(54) Title: COMBINING FOCUSED ION BEAM MILLING AND SCANNING ELECTRON MICROSCOPE IMAGING

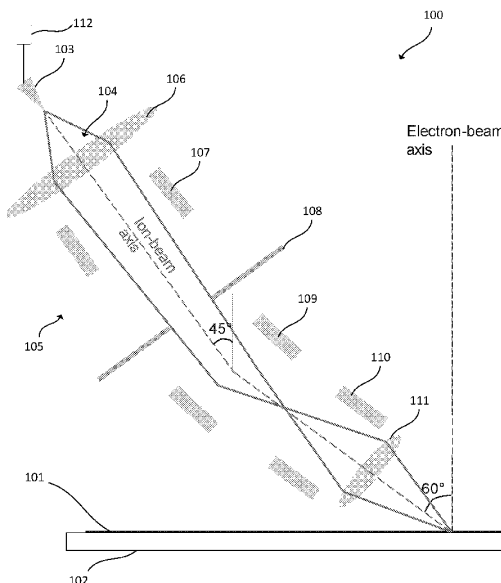


FIG. 2

(57) Abstract: The dual focused ion beam and scanning electron beam system includes an electron source that generates an electron beam and an ion source that generates an ion beam. The electron beam column directs an electron beam at a normal angle relative to a top surface of the stage. An ion beam column directs the ion beam at the stage. The ion beam is at an angle relative to the electron beam. A detector receives the electron beam reflected from the wafer on the stage.

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Published:

— with international search report (Art. 21(3))